



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2023-05-31
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Floriana SAN BIAGIO	Representative title	AMS Material Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
	ICEH*UBECAZS	A	994D	2023-05-31
Amount	Unit of measure	Unit type	ST ECOPACK grade	
68	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		
Package designator	Package size	Number of instances	Shape	
QFN	5 x 5	68	Flat	
Comment	A0EH VFQFPN 40L 5X 5X1 0,4 PITCH; MDF is valid for PM6779TR			



QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
QUERY		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : California Prop65 list, dated 27th Jan 2023			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.368	alloy	5380
Lead	0.000		0
Lead-Borate Glass	0.000		0
Lead Zirconate Titanate	0.000		0
Antimony trioxide	0.000		0
Bisphenol A	0.000		0

QueryList : REACH-17th Jan 2023				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
,			,	

QueryList : Responsible metals sourcing		Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.		true
The following metals are present is the component :		Cobalt, Gold, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				Response
The Product does contain at least one of the substances listed in Chemical Control Act				false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020		Response
The product contains adhesives identified under GB 33372		false

Stockholm Convention Persistent Organic Pollutants		Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I		true



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ICEH*UBECAZS		68.4002		5000002.0	1000002.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	5.338	mg	supplier	die	Silicon(Si)	7440-21-3		5.034	mg	943050	73596
				supplier	metallisation	Aluminium(AI)	7429-90-5		0.094	mg	17610	1374
				supplier	metallisation	Copper(Cu)	7440-50-8		0.016	mg	2997	234
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.001	mg	187	15
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.005	mg	937	73
				supplier	metallisation	Tungsten(W)	7440-33-7		0.009	mg	1686	132
				supplier	passivation	Silicon oxide	7631-86-9		0.179	mg	33533	2617
				supplier	alloy	Copper (Cu)	7440-50-8		37.405	mg	965415	546857
				supplier	alloy	Iron (Fe)	7439-89-6		0.883	mg	22790	12909
				supplier	alloy	Phosphorus (P)	7723-14-0		0.012	mg	310	175
Leadframe	M-004 Copper and its alloys	38.745	mg	supplier	alloy	Zinc (Zn)	7440-66-6		0.058	mg	1497	848
				supplier	metallization	Nickel (Ni)	7440-02-0		0.368	mg	9498	5380
				supplier	metallization	Palladium (Pd)	7440-05-3		0.015	mg	387	219
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	103	58
				supplier	glue	Modified Epoxy Resin	Proprietary		0.209	mg	649597	3060
				supplier	glue	Epoxy resin	29690-82-2		0.081	mg	249845	1177
				supplier	glue	Aromatic polyamine	Proprietary		0.010	mg	30106	142
				supplier	glue	Modified Siloxane	Proprietary		0.013	mg	40037	189
Die attach	M-015 Other organic materials	0.322	mg	supplier	glue	Silane	Proprietary		0.005	mg	14898	70
				supplier	glue	Epoxy Resin	25068-38-6		0.005	mg	15518	73
				supplier	wire	Gold (Au)	7440-57-5		0.119	mg	991667	1740
				supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	8333	15
				supplier	mold compound	Epoxy resin	Proprietary		2.414	mg	101110	35292
Bonding wires	M-008 Precious metals	0.120	mg	supplier	wire	Gold (Au)	7440-57-5		0.119	mg	991667	1740
				supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	8333	15
				supplier	mold compound	Phenol resin	Proprietary		1.278	mg	53529	18684
				supplier	mold compound	Silica(Amorphous) A	60676-86-0		17.627	mg	738304	257705
				supplier	mold compound	Silica(Amorphous) B	7631-86-9		2.414	mg	101110	35292
Encapsulation	M-015 Other organic materials	23.875	mg	supplier	mold compound	Carbon black	1333-86-4		0.142	mg	5948	2076